

半田×接着剤の複合材料 半田接続と樹脂補強を一括形成!

Solder x Adhesive Composite material
Solder connection and resin reinforcement are collectively formed



半田接続型異方導電性接着剤(ACA)

Solder connection type Anisotropic Conductive Adhesive

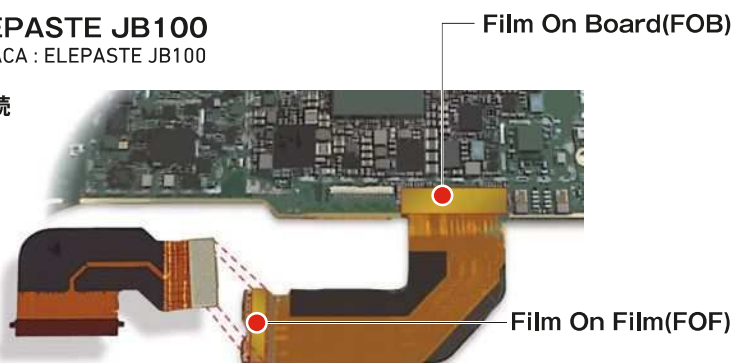
特長 Features

- 半田接続による優れた接続信頼性
Good connection reliability due to solder connection
- 低温接続可能
Low temperature connection is possible
- 窒素雰囲気不要
N₂ atmosphere unnecessary
- 接続用途の異なる2タイプをラインナップ
Two types of products with different connection applications
 1. 熱圧着型ACA: ELEPASTE JB100
Thermal crimping type ACA: ELEPASTE JB100
 2. 半田粒子集合型ACA(開発品)
Solder particle assembly type ACA (under development)

用途 Application

- 熱圧着型ACA: ELEPASTE JB100
Thermal crimping type ACA: ELEPASTE JB100

- FOB接続, FOF接続
FOB / FOF connection



- 半田粒子集合型ACA(開発品)
Solder particle assembly type ACA (under development)

- Mini-LED実装
Mini-LED mounting material

